

ICS 29.045
CCS H 82



**NATIONAL STANDARD OF THE
PEOPLE'S REPUBLIC OF CHINA**

GB/T 6620-2009

Replacing GB/T 6620-1995

**Test method for measuring warp on silicon slices by
noncontact scanning**

硅片翘曲度非接触式测试方法

(English Translation)

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What this standard covers

This standard specifies the monocrystalline silicon cutting discs, grinding pieces, polished (hereinafter referred to as silicon) warpage non-contact testing methods. This standard for measuring a diameter greater than 50 mm, a thickness greater than 180 μm circular wafers. This standard is also applicable to other semiconductor measuring warpage picture card. The purpose of this test method is used for incoming inspection or process control. This test method is also suitable for hot chemistry monitoring device wafers during processing of warpage.

Document data

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Standards quoted by this document

GB/T 2828.1; GB/T 6618; GB/T 14264